

*AMENDMENTS TO THE CLAIMS*

This listing of claims replaces all prior versions, and listings, of claims in the application.

1. (Currently Amended) A package for an optical semiconductor device comprising:

a stem having an under surface, an upper surface, a mount ~~to be mounted, with on the upper surface for mounting of an optical semiconductor device, on the upper surface,~~ and at least one through hole having a diameter and penetrating from the upper surface to the under surface, ~~and~~

a lead terminal for signal supply, having a central axis transverse to the upper surface, penetrating one of the through holes, and insulated by an insulator from the stem, ~~wherein the upper surface has and~~

an earth conductor on the upper surface, adjacent to the lead terminal for signal supply, projecting from the upper surface, and having a circumferential face transverse to the upper surface, opposite the lead terminal for signal supply, and extending at least 150° around the central axis of the lead terminal for signal supply.

Claims 2 and 3 (Cancelled).

4. (Withdrawn) The package for an optical semiconductor device according to claim 1, wherein the earth conductor includes the mount monolithically.

5. (Withdrawn) The package for an optical semiconductor device according to claim 1, wherein the earth conductor overlaps with the insulator.

6. (Withdrawn) The package for an optical semiconductor device according to claim 1 including a dielectric member located between the earth conductor and the lead terminal for signal supply.

7. (Withdrawn) The package for an optical semiconductor device according to claim 1 including earth electrode terminals on opposite sides of the terminal for signal supply projecting from the under surface of the stem.

8. (Withdrawn) The package for an optical semiconductor device according to claim 1, wherein the earth electrode terminals are monolithically integrated with the stem.

9. (Withdrawn) The package for an optical semiconductor device according to claim 1 further comprising a second lead terminal for signal supply pairing with the lead terminal for signal supply.

10. (Withdrawn) The package for an optical semiconductor device according to claim 1, wherein the earth conductor includes the mount monolithically and the mount is attached to the stem so that the earth conductor overlaps the insulator.

11. (Withdrawn) The package for an optical semiconductor device according to claim 1, wherein the mount and the stem are produced by press processing, respectively.

12. (Withdrawn) The package for an optical semiconductor device according to claim 10, wherein distance between the earth conductor and the lead terminal for signal supply provides a characteristic impedance of a transmission line constituted by the lead terminal for signal supply projecting from the upper surface of the stem of no more than 60 ohms.

13. (Withdrawn) The package for an optical semiconductor device according to claim 10, wherein distance between the earth conductor and the lead terminal for signal supply is no more than 0.175mm.

14. (Withdrawn) The package for an optical semiconductor device according to claim 10 further comprising a guide for positioning the mount on the upper surface of the stem.

15. (Withdrawn) The package for an optical semiconductor device according to claim 12, wherein a tip portion of the lead terminal for signal supply is deformed so that the characteristic impedance of said transmission line is reduced.

16. (Withdrawn) The package for an optical semiconductor device according to claim 15, wherein said lead terminal for signal supply has a cylinder shape and the tip portion is deformed by crushing the cylinder shape into a flat portion.

17. (Withdrawn) The package for an optical semiconductor device according to claim 15, wherein a face of the earth conductor surrounding the lead terminal is crooked along with the tip portion of said lead terminal for signal supply.

18. (Withdrawn) The package for an optical semiconductor device according to claim 10, wherein the mount has a step at a corner in the portion of said earth conductor overlapping the insulator so that the earth conductor does not directly contact the insulator.

19. (Withdrawn) The package for an optical semiconductor device according to claim 10, wherein the mount is located on the upper surface of the stem and including a plinth between the mount and the stem in the portion of the earth conductor overlapping the insulator so that the earth conductor does not directly contact the insulator.

20. (Withdrawn) The package for an optical semiconductor device according to claim 10, wherein the mount has a corner with a circumferential shape in the portion of the earth conductor overlapping the insulator so that the earth conductor does not directly contact the insulator.

21. (New) The package for an optical semiconductor device according to claim 1, wherein the circumferential face lies along a circumference of a circle having, on the upper surface, a diameter not exceeding the diameter of the through hole.

22. (New) The package for an optical semiconductor device according to claim 21, wherein the circle along which the circumferential surface lies is coaxial with the lead terminal for signal supply.